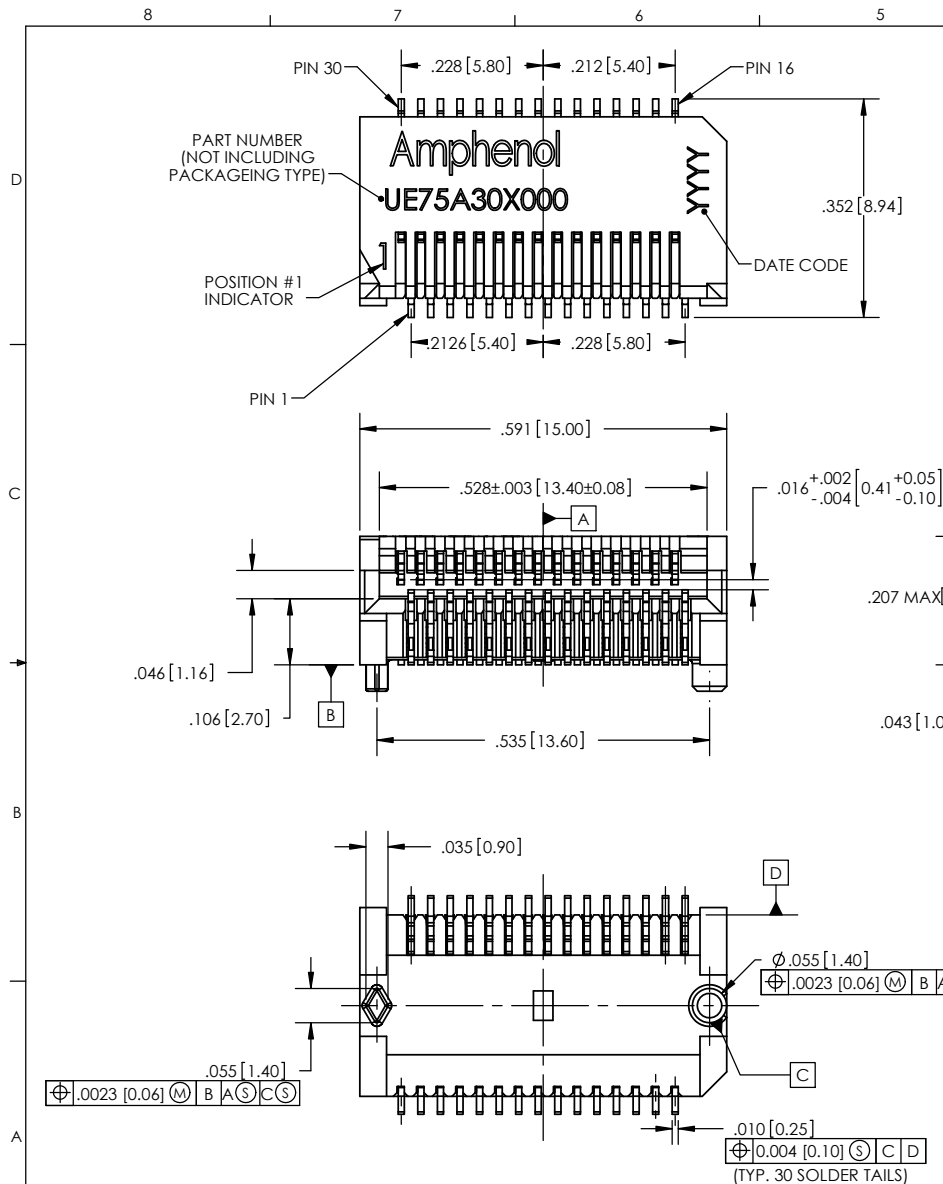




DO NOT SCALE DRAWING

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

REVISIONS				
REV.	ZONE	DESCRIPTION	DATE	APPROVED
E		PLATING 5 & 6 ADDED	2007/04/05	A.G
F		MATING END GAP DIM. ADDED	2008/09/03	A.G
G		DRAWING UPDATE	2012/03/21	ZLJ
H		DRAWING UPDATE	2012/10/26	ZLJ

PLASTIC HOUSING:
HIGH TEMPERATURE RESISTANT PLASTIC
COLOUR: BLACK
FLAMABILITY RATING UL94V-0

PACKAGING:
TAPE AND REEL RACKAGING

TEMPERATURE RANGE:
-40°C TO +85°C

MATERIAL NOTES
CONTACTS:
PHOSPHOR BRONZE

PLATING OPTION 2: (RoHS FOR UE75 ONLY)
30µ" [0.76 µm] MIN. GOLD ON MATING
AREA AND 2µ" [0.05 µm] GOLD FLASH
PLATING ON TERMINATION OVER 50µ"
[1.27 µm] MIN. NICKEL UNDER LAYER

PLATING OPTION 3: (RoHS FOR UE75 ONLY)
30µ" [0.76 µm] MIN. GOLD ON MATING
AREA AND 100 - 150µ" [3.81 - 7.62 µm]
MIN. LOW WHISKER MATTE TIN PLATING
ON TERMINATION OVER 50µ" [1.27 µm]
MIN. NICKEL UNDER LAYER

PLATING OPTION 5: (RoHS FOR UE75 ONLY)
15µ" [0.38 µm] MIN. GOLD ON MATING
AREA AND 2µ" [0.05 µm] GOLD FLASH
PLATING ON TERMINATION OVER 50µ"
[1.27 µm] MIN. NICKEL UNDER LAYER

PLATING OPTION 6: (RoHS FOR UE75 ONLY)
15µ" [0.38 µm] MIN. GOLD ON MATING
AREA AND 100 - 150µ" [3.81 - 7.62 µm]
MIN. LOW WHISKER MATTE TIN PLATING
ON TERMINATION OVER 50µ" [1.27 µm]
MIN. NICKEL UNDER LAYER



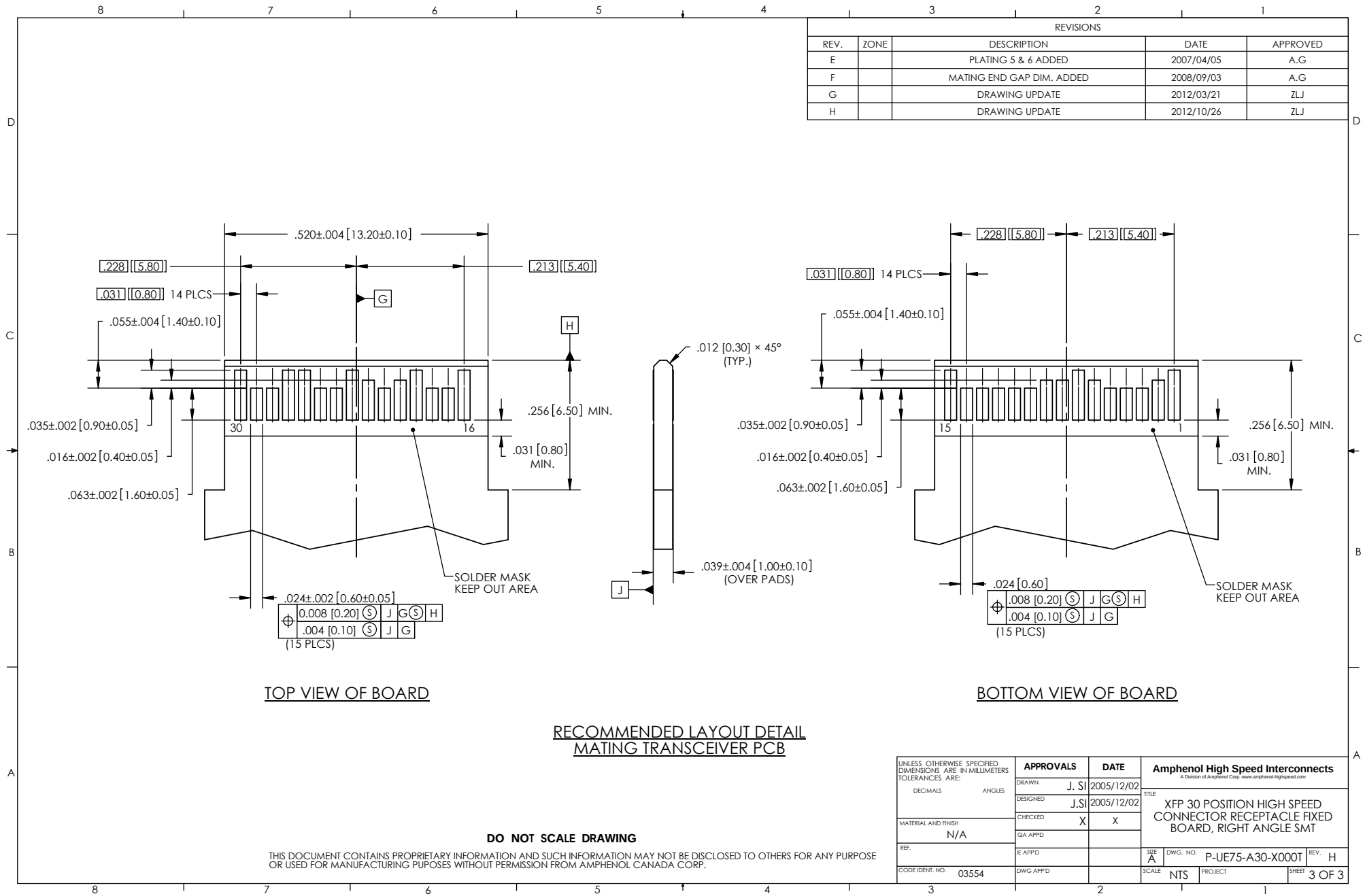
AMPHENOL PART NUMBER CONFIGURATION

UE75 - A 30 - X 0 0 0 T

CONTACT PLATING (SEE MATERIAL NOTES)

(FOR UE75 RoHS)
2 = PLATING OPTION 2
3 = PLATING OPTION 3
5 = PLATING OPTION 5
6 = PLATING OPTION 6

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: DECIMALS ANGLES		APPROVALS		DATE	Amphenol High Speed Interconnects A Division of Amphenol Corp. www.amphenolhighspeed.com			
		DRAWN	J. SI	2005/12/02	TITLE	XFP 30 POSITION HIGH SPEED CONNECTOR RECEPTACLE FIXED BOARD, RIGHT ANGLE SMT		
		DESIGNED	J.SI	2005/12/02				
		CHECKED	X	X				
MATERIAL AND FINISH N/A		QA APP'D			SIZE A			
REF.		E APP'D						
CODE IDENT. NO.	03554	DWG APP'D			SCALE NTS	PROJECT	SHEET 1 OF 3	



REVISIONS				
REV.	ZONE	DESCRIPTION	DATE	APPROVED
E		PLATING 5 & 6 ADDED	2007/04/05	A.G
F		MATING END GAP DIM. ADDED	2008/09/03	A.G
G		DRAWING UPDATE	2012/03/21	ZLJ
H		DRAWING UPDATE	2012/10/26	ZLJ

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: DECIMALS ANGLES MATERIAL AND FINISH N/A REF. CODE IDENT. NO. 03554		APPROVALS		DATE		Amphenol High Speed Interconnects A Division of Amphenol Corp. www.amphenol-highspeed.com TITLE XFP 30 POSITION HIGH SPEED CONNECTOR RECEPTACLE FIXED BOARD, RIGHT ANGLE SMT SIZE A DWG. NO. P-UE75-A30-X000T REV. H SCALE NTS PROJECT SHEET 3 OF 3	
		DRAWN	J. SI	2005/12/02			
		DESIGNED	J. SI	2005/12/02			
		CHECKED	X	X			
		QA APPD					
		E APPD					
		DWG APPD					

DO NOT SCALE DRAWING

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Amphenol:](#)

[UE75-A30-5000T](#)